# MA36132E

## Silicon epitaxial planar type

For high speed switching circuits

### ■ Features

- Two elements are contained in one package, optimum for high-density mounting
- Short reverse recovery time $t_{rr}$
- Small terminal capacitance $C_t$

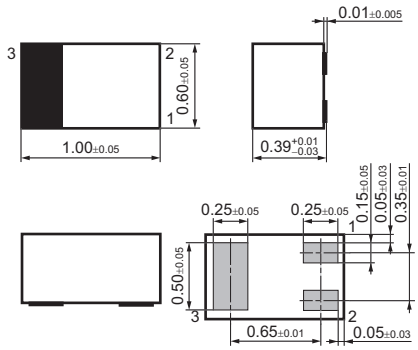
### ■ Absolute Maximum Ratings $T_a = 25°C$

| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Reverse voltage | $V_R$ | 80 | V |
| Maximum peak reverse voltage | $V_{RM}$ | 80 | V |
| Forward current | $I_F$ | 150 | mA |
| | | 100 *2 | |
| Forward current (Average) | $I_{FM}$ | 340 | mA |
| | | 225 *2 | |
| Non-repetitive peak forward surge current *1 | $I_{FSM}$ | 750 | mA |
| | | 500 *2 | |
| Junction temperature | $T_j$ | 150 | °C |
| Storage temperature | $T_{stg}$ | –55 to +150 | °C |

Note) *1: t = 1 s

*2: Value for single diode

Unit: mm

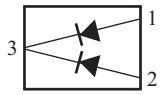



1: Anode 1
2: Anode 2
3: Cathode 1, 2

ML3-N2 Package

Marking Symbol: A2

Internal Connection



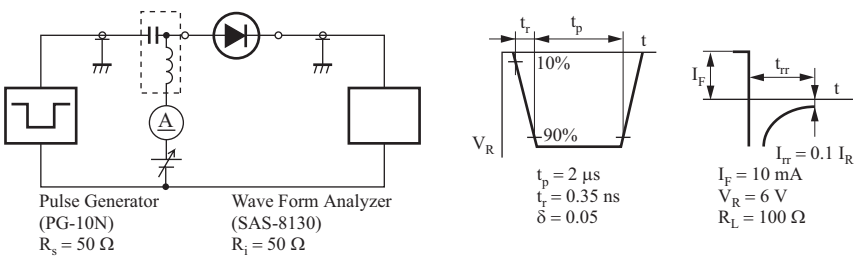

### ■ Electrical Characteristics $T_a = 25°C \pm 3°C$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| Forward current | $V_F$ | $I_F$ = 100 mA | | | 1.2 | V |
| Reverse voltage | $V_R$ | $I_R$ = 100 μA | 80 | | | V |
| Reverse current | $I_R$ | $V_R$ = 75 V | | | 100 | nA |
| Terminal capacitance | $C_t$ | $V_R$ = 0, f = 1 MHz | | | 2 | pF |
| Reverse recovery time * | $t_{rr}$ | $I_F$ = 10 mA, $V_R$ = 6 V, $I_{rr}$ = 0.1 $I_R$, $R_L$ = 100 Ω | | | 3 | ns |

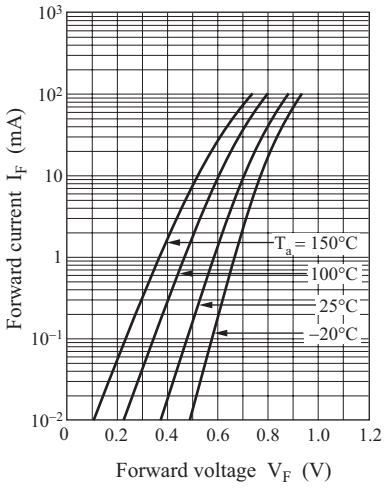
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

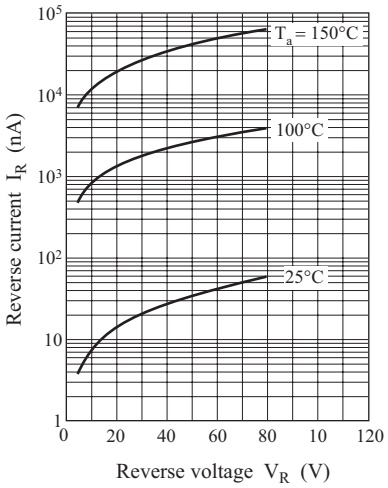
3. *: $t_{rr}$ measurement circuit



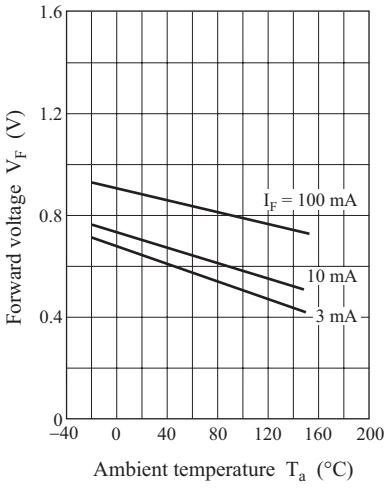
$I_F$ — $V_F$



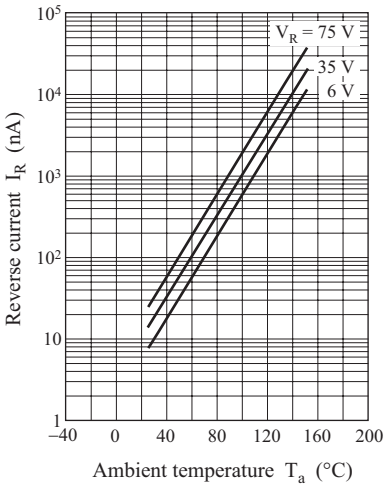

$I_R$ — $V_R$



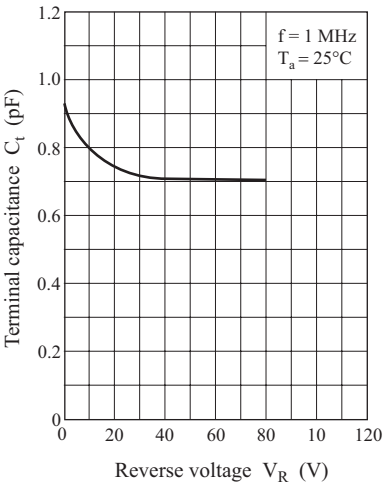

$V_F$ — $T_a$



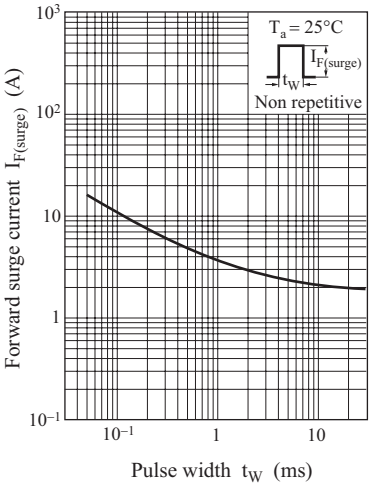

$I_R$ — $T_a$




$C_t$ — $V_R$




$I_{F(surge)}$ — $t_W$



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